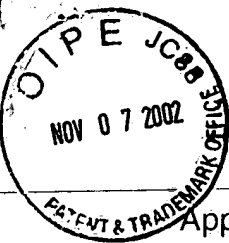


32/Suppl. IDS
DKing
1/28/03

EV182661147



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/388,826
Filing Date September 1, 1999
Inventor Weimin (Michael) Li et al.
Assignee Micron Technology, Inc.
Group Art Unit 2813
Examiner E. Kielin
Attorney's Docket No. 22-1208
Title: Low k Interlevel Dielectric Layer Fabrication Methods

RECEIVED
NOV 13 2002
TECHNOLOGY CENTER 2800

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References - See Attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

Dated: Nov. 7, 2002

By: 
Frederick M. Fliegel, Ph.D.
Reg. No. 36,138

11/13/2002 HMEKONEN 00000059 09388826

01 FC:1806

180.00 DP